

AMENDMENTS TO THE CLAIMS

Claim 1 (Withdrawn). A heat-treated resin molding obtained by heat-treating a specific portion of a resin molding (W) partially at a high temperature which specific portion is apt to undergo peeling of a thin surface resin film of the resin molding (W), the resin molding (W) being produced by molding with use of a mold and to be subjected to plating with resin.

Claim 2 (Canceled).

Claim 3 (Withdrawn). A heat-treated resin molding according to claim 1, wherein a parting line portion (W1) of the resin molding (W) is heat-treated at a high temperature.

Claim 4 (Canceled).

Claim 5 (Withdrawn). A heat-treated resin molding according to claim 1, wherein the resin molding (W) is heat-treated at a high temperature so that rubber particles in the resin surface of the resin molding retain a generally circular shape.

Claim 6 (Withdrawn). A heat-treated resin molding according to claim 1, wherein the resin molding (W) is heat-treated so that rubber particles in the resin surface of the resin molding retain a circular shape of 2:3 or less in terms of a size ratio in longitudinal and transverse directions.

Claim 7 (Withdrawn). A heat-treated resin molding according to claim 1, wherein the resin molding (W) to be partially heat-treated at a high temperature is a resin molding produced

by molding in an injection molding machine.

Claim 8 (Previously Presented). A resin molding heat-treating apparatus (1) for partially heat-treating ~~a parting line portion (W1) of a resin molding (W) at a high temperature or a specific portion of the resin molding (W), which portion is apt to undergo peeling of a thin surface resin film, partially at a high temperature,~~ the apparatus (1) comprising:

a heating section (2) having a shape conforming to a contour line of a portion of the resin molding (W) to be heated, including a contour line of an end of the portion; ~~of the resin molding (W);~~ and

a fixing jig (4) for fixing the resin molding (W) removably,

wherein the heating section partially heat-treats a parting line portion (W1) of the resin molding or a specific portion of the resin molding (W) which is apt to undergo peeling of a thin surface resin film; the portion to be heated of the resin molding (W) is heat-treated at a high temperature while being approximated to the heating section (2).

Claim 9 (Currently Amended). A resin molding heat-treating apparatus according to claim 8, wherein the fixing jig (4) is attached to several positions of a rotary disc (3) and the portion to be heated of the resin molding (W) projects from ~~[[the]]~~ a peripheral edge of the rotary disc (3) so as to pass through a heat-treating space (S) formed in the heating section (2).

Claim 10 (Previously Presented). A resin molding heat-treating apparatus according to claim 8, wherein a shield plate (8) having an opening portion (7) of a shape conforming to the contour line of the portion to be heated of the resin molding (W) is disposed in a sandwiching relation to the heating section (2) so that the other portion than the portion to be heated of the

resin molding (W) is not heated.

Claim 11 (Original). A resin molding heat-treating apparatus according to claim 8, wherein the fixing jig (4) is attached to several positions of a side edge of a belt member and the portion to be heated of the resin molding (W) projects from the belt member so as to pass through a heat-treating space (S) formed in the heating section (2).

Claim 12 (Original). A resin molding heat-treating apparatus according to claim 8, wherein the heating section (2) is constructed such that a large number of fine holes are formed in a pipe which is analogous to the contour line of the resin molding (W) and which is bent so as to be in a shape about twice as large as the resin molding (W), and hot air is ejected through the fine holes to heat the resin molding.

Claim 13 (Original). A resin molding heat-treating apparatus according to claim 8, wherein the heating section (2) is constructed such that a member analogous to the contour line of the resin molding (W) and having a shape about twice as large as the resin molding (W) is heated by an electromagnetic induction heating method.

Claim 14 (Original). A resin molding heat-treating apparatus according to claim 8, wherein the heating section (2) is constructed such that a member analogous to the contour line of the resin molding (W) and having a shape about twice as large as the resin molding (W) is heated by a high-frequency heating method.

Claim 15 (Withdrawn). A heat-treated resin molding according to claim 3, wherein the

resin molding (W) is heat-treated at a high temperature so that rubber particles in the resin surface of the resin molding retain a generally circular shape.

Claim 16 (Withdrawn). A heat-treated resin molding according to claim 3, wherein the resin molding (W) is heat-treated so that rubber particles in the resin surface of the resin molding retain a circular shape of 2:3 or less in terms of a size ratio in longitudinal and transverse directions.

Claim 17 (Withdrawn). A heat-treated resin molding according to claim 5, wherein the resin molding (W) is heat-treated so that rubber particles in the resin surface of the resin molding retain a circular shape of 2:3 or less in terms of a size ratio in longitudinal and transverse directions.

Claim 18 (Withdrawn). A heat-treated resin molding according to claim 15, wherein the resin molding (W) is heat-treated so that rubber particles in the resin surface of the resin molding retain a circular shape of 2:3 or less in terms of a size ratio in longitudinal and transverse directions.

Claim 19 (Withdrawn). A heat-treated resin molding according to claim 3, wherein the resin molding (W) to be partially heat-treated at a high temperature a resin molding produced by molding in an injection molding machine.

Claim 20 (Previously Presented). A resin molding heat-treating apparatus according to claim 9, wherein a shield plate (8) having an opening portion (7) of a shape conforming to the

contour line of the portion to be heated of the resin molding (W) is disposed in a sandwiching relation to the heating section (W) so that the other portion than the portion to be heated of the resin molding (W) is not heated.

Claim 21 (New): A resin molding heat-treating apparatus according to claim 8, wherein the apparatus is suitable for a resin molding (W) comprising two or more different resins and containing a rubbery or oil- or fat- substance.